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FORM PTO-1595  
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COVER SHEET  
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7257/59401

To the Honorable Commissioner of Patents and Trademarks

and the attached original documents or copy thereof.

1. Name of conveying party(ies):

Wei-Chung Wang No. 2-107, Sun-Pu-Pei Lane Niao-Sung Village Niao-Sung Hsiang Kaohsiung Hsien, Taiwan R.O.C.	Hsueh-Te Wang No. 11-4, Li-Te Lane Pen-Kuan Rd. Niao-Sung Hsiang Kaohsiung Hsien, Taiwan R.O.C.
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Jen-Kuang Fang No. 67, Nan-Chin Rd. Kang-Hsi Village Hsin-Yuan Hsiang Pingtung Hsien, Taiwan R.O.C.	Su Tao No. 72-2 Chung-Shih-Hsin Village Kaohsiung, Taiwan R.O.C.
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Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies):

Name: Advanced Semiconductor Engineering, Inc.

Internal Address: \_\_\_\_\_

Street Address: 26, Chin 3rd Rd., 811, Nantze Export

Processing Zone \_\_\_\_\_

City Kaohsiung State Taiwan, R.O.C. ZIP \_\_\_\_\_

Additional name(s) & address(es) attached?  Yes  No

09317354

525 U.S. PTO  
09/317354  
05/24/99

3. Nature of Conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other \_\_\_\_\_

Execution Date: May 18, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: May 18, 1999

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William E. Pelton, Esq.

Internal Address: Cooper & Dunham LLP

Street Address: 1185 Avenue of the Americas

06/04/1999 PEOPLES 00000017 09317354  
02 FC:587: New York State: New York ZIP 10036 40.00 DP

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): . . . . . \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

03-3125

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William E. Pelton, Reg. No. 25,702  
Name of Person Signing

William E. Pelton  
Signature

May 24, 1999  
Date

Total Number of pages comprising cover sheet: 2

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PATENT  
REEL: 009997 FRAME: 0974

# ASSIGNMENT

- (1) Wei-Chung WANG  
(2) Hsueh-Te WANG  
(3) Jen-Kuang FANG  
(4) Su TAO  
(5) \_\_\_\_\_

(1-5) Insert Name(s) of Inventor(s).

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(6) Insert name of Assignee

- (6) Advanced Semiconductor engineering, Inc.  
(7) 26, Chin 3rd Rd., 811, Nantze Export Processing Zone, Kaohsiung, Taiwan, R.O.C.

(7) Insert address of Assignee

(hereinafter designated as the Assignee) the entire right, title and interest for the United States, its territories, dependencies and possessions, in the invention, and all applications for patent and any Letters Patent which may be granted therefor, known as

(8) Insert Identification of Invention, such as Title, Case Number or Foreign Application Number

- (8) Flip-Chip Semiconductor Device with Enhanced Reliability and Manufacturing Efficiency, and the Method for under Filling the

Foreign Application or Case No.
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Same for which the undersigned has (have) executed an application for patent in the United States of America

(9) Insert Date of Signing of Application

- (9) on May 18, 1999

(10) Alternative identification for filed applications

- (10) U.S. application Serial Number \_\_\_\_\_, filed \_\_\_\_\_

1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient or essential to its full protection and title in and to the invention hereby transferred.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division or re-issue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

4) The undersigned agree(s) to communicate to the Assignee or representatives thereof any facts known to me (us) respecting the invention and improvements thereof, and will, upon request, but without expense to me (us), testify in any legal proceedings regarding the invention.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

6) The undersigned hereby grant(s) the firm of Cooper & Dunham the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

7) This Assignment shall be binding upon my (our) heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns of the Assignee.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

- (1) Date May 18, 1999 Name of Inventor Wei Chung Wang  
(2) Date May 18, 1999 Name of Inventor Hsueh Te Wang  
(3) Date May 18, 1999 Name of Inventor FANG JEN KUANG  
(4) Date May 18, 1999 Name of Inventor Su Tao  
(5) Date \_\_\_\_\_ Name of Inventor \_\_\_\_\_

Date \_\_\_\_\_ Witness \_\_\_\_\_

Date \_\_\_\_\_ Witness \_\_\_\_\_